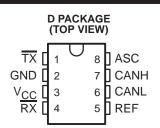
- SN75LBC031 Meets Standard ISO/DIS 11898 (up to 500 k Baud)
- Driver Output Capability at 50 mA
- Wide Positive and Negative Input/output Bus Voltage Range
- Bus Outputs Short-Circuit-Protected to Battery Voltage and Ground
- Thermal Shutdown
- Available in Q-Temp Automotive
 - HighRel Automotive Applications
 - Configuration Control/Print Support
 - Qualification to Automotive Standards

description

The SN75LBC031 is a CAN transceiver used as an interface between a CAN controller and the physical bus for high speed applications of up to 500 kBaud. The device provides transmit capability to the differential bus and differential receive capability to the controller. The transmitter outputs (CANH and CANL), feature internal transition regulation to provide controlled symmetry resulting in low EMI emissions. Both



SLRS048A - MAY 1998 - REVISED APRIL 2000

TERMINAL FUNCTIONS

TERMINAL	DESCRIPTION			
TX	Transmitter input			
GND	Ground			
V _{CC}	Supply voltage			
RX	Receiver output			
REF	Reference output			
CANL	Low side bus output driver			
CANH	High side bus output driver			
ASC	Adjustable slope control			

FUNCTION TABLE									
TX CANH CANL BUS STATE									
L	Н	L	Dominant	L					
High or floating	Floating	Floating	Recessive	Н					
L = low, H = high									

transmitter outputs are fully protected against battery short circuits and electrical transients that can occur on the bus lines. In the event of excessive device power dissipation the output drivers are disabled by the thermal shutdown circuitry at a junction temperature of approximately 160°C. The inclusion of an internal pullup resistor on the transmitter input ensures a defined output during power up and protocol controller reset. For normal operation at 500 kBaud the ASC terminal is open or tied to GND. For slower speed operation at 125 kBaud the bus output transition times can be increased to reduce EMI by connecting the ASC terminal to V_{CC}. The receiver includes an integrated filter that suppresses the signal into pulses less than 30 ns wide.

The SN75LBC031 is characterized for operation from –40°C to 85°C. The SN65LBC031 is characterized for operation from –40°C to 125°C. The SN65LBC031Q is characterized for operation over the automotive temperature range of –40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

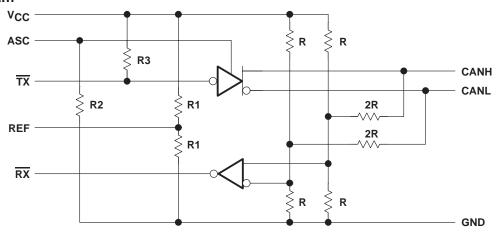
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2000, Texas Instruments Incorporated

SLRS048A - MAY 1998 - REVISED APRIL 2000

logic diagram





SLRS048A - MAY 1998 - REVISED APRIL 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Logic supply voltage, V _{CC} (see Note 1)	
Bus terminal voltage	
Input current at \overline{TX} and ASC terminal, I ₁	±10 mA
Input voltage at \overline{TX} and ASC terminal, V_1	$\dots 2 \times V_{CC}$
Operating free-air temperature range, T _A : SN65LBC031, SN65LBC031Q	40°C to125°C
SN75LBC031	−40°C to 85°C
Operating juncation range, T _J	$\dots -40^{\circ}C$ to $150^{\circ}C$
Continuous total power dissipation at (or below) 25°C free-air temperature See Dis	sipation Rating Table
Storage temperature range, T _{stg}	−65°C to 150°C
Case temperature for 10 sec T _C , D package	260°C

 [†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: All voltage values, except differential bus voltage, are measured with respect to GND.

> **DISSIPATION RATING TABLE** $T_A \le 25^{\circ}C$ **OPERATING FACTOR** T_C = 125°C PACKAGE POWER RATING POWER RATING ABOVE T_C = 25°C D 725 mW 5.8 mW/°C 145 mW **DISSIPATION DERATING CURVE** VS **FREE-AIR TEMPERATURE** 1200 T_C = 25°C P_D – Maximum Continuous Dissipation – mW 1000 P = 8.8 mW/°C 800 600 D = 5.8 mW/°C 400 200 0 25 35 45 55 65 75 85 95 105 115 125 T_A – Free-Air Temperature – °C Figure 1

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SLRS048A - MAY 1998 - REVISED APRIL 2000

recommended operating conditions

		MIN	NOM	MAX	UNIT
Logic supply voltage, VCC		4.5	5	5.5	V
Voltage at any bus terminal (separately or common mode), VI or VIC (see Note 3)				7	V
High-level input voltage, VIH	TX	2		VCC	V
Low-level input voltage, V_{IL}	TX	0		0.8	V
I Pade Law a based as summary 1	Transmitter			-50	mA
High-level output current, IOH	Receiver			-400	μΑ
	Transmitter			50	
Low-level output current, IOL	Receiver			1	mA
	SN75LBC031	-40		85	**
Operating free-air temperature, T_A	SN65LBC031, SN65LBC031Q	-40		125	°C

NOTES: 2. All voltage values, except differential bus voltage, are measured with respect to the ground terminal.

3. For bus voltages from -5 V to -2 V and 7 V to 20 V the receiver output is stable.

DATA SHEET PARAMETER	DEFINITION					
VO(CANHR)	CANH bus output voltage (recessive state)					
VO(CANLR)	CANL bus output voltage (recessive state)					
VO(CANHD)	CANH bus output voltage (dominant state)					
VO(CANLD)	CANL bus output voltage (dominant state)					
VO(DIFFR)	Bus differential output voltage (recessive state)					
V _O (DIFFD)	Bus differential output voltage (dominant state)					
V _{I(ASC)}	Adjustable slope control input voltage					

SYMBOL DEFINITION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VO(REF)	Reference source output voltage	$I_{REF} = \pm 20 \ \mu A$	0.45 V _{CC}		0.55V _{CC}	V
R _{O(REF)}	Reference source output resistance		5		10	kΩ
ICC(REC)	Logic supply current, recessive state	See Figure 2, S1 closed		12	20	mA
ICC(DOM)	Logic supply current, dominant state	See Figure 2, ST Closed		55	80	ША



SLRS048A - MAY 1998 - REVISED APRIL 2000

transmitter electrical characteristics over recommended ranges of supply and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VO(CANHR) VO(CANLR)	Output voltage (recessive state)	See Figure 2, S1 open	2	0.5V _{CC}	3	V
VO(DIFFR)	Differential output voltage (recessive state)		-500	0	50	mV
VO(CANHD)	Output voltage (dominant state)		2.75	3.5	4.5	
VO(CANLD)	Output voltage (dominant state)	See Figure 2, S1 closed	0.5	1.5	2.25	V
VO(DIFFD)	Differential output voltage (dominant state)		1.5	2	3	
	High-level input current (TX)	V _{IH} = 2.4 V		-100	-185	μA
lih(tx)		$V_{IH} = V_{CC}$			±2	μΑ
	High-level input current (ASC)	V _{IH} = 2.4 V		100	165	μA
^I IH(ASC)	nigh-level input current (ASC)	$V_{IH} = V_{CC}$		200	340	μΑ
I _{IL(TX)}	Low-level input current (\overline{TX})	V _{IL} = 0.4 V		-180	-400	μΑ
IIL(ASC)	Low-level input current (ASC)	V _{IL} = 0.4 V		15	25	μA
C _{I(TX)}	TX input capacitance			8		pF
I _{O(ssH)}	CANH short circuit output current	$V_{O(CANH)} = -2 V \text{ to } 20 V$		-95	-200	mA
I _{O(ssL)}	CANL short circuit output current	$V_{O(CANL)} = 20 V \text{ to } -2 V$		140	250	mA

NOTE 2: All voltage values, except differential bus voltage, are measured with respect to the ground terminal.

transceiver dynamic characteristics over recommended operating free-air temperature range and V_{CC} = 5 V

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
4		See Figures 2 and 3, S1 closed,	VI(ASC) = 0 V or open circuit, S2 open			280	ns
^t (loop)	Loop time	See Figures 2 and 3, S1 closed,	VI(ASC) = V _{CC} , S2 closed			400	ns
00	Differential-output slew rate	See Figures 2 and 4, S1 closed,	VI(ASC) = 0 or open circuit, S2 open		35		V/µs
SR _(RD)	(recessive to dominant)	See Figures 2 and 4, S1 closed,	VI(ASC) = V _{CC} , S2 closed		10		V/µs
	Differential-output slew rate	See Figures 2 and 4, S1 closed,	VI(ASC) = 0 or open circuit, S2 open		10		V/µs
SR _(DR)	(dominant to recessive)	See Figures 2 and 4, S1 closed,	VI(ASC) = VCC, S2 closed		10		V/µs
^t d(RD)	Differential output delay time		S1 alagad		55		ns
^t d(DR)	Differential-output delay time	See Figure 2,	S1 closed		160		ns
^t pd(RECRD)	Receiver propagation delay	See Figures 2 and 5			90		ns
^t pd(RECDR)	time	See rigules 2 and 5			55		ns

NOTE 4: Receiver input pulse width should be >50 ns. Input pulses of <30 ns are suppressed.

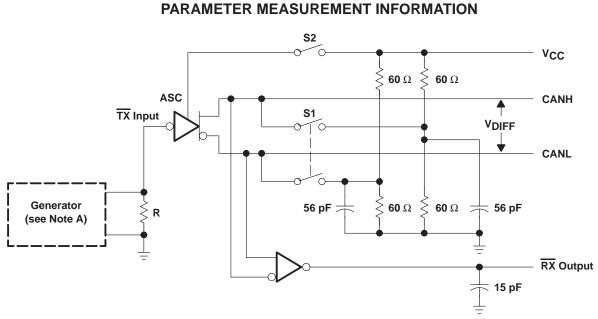


SLRS048A - MAY 1998 - REVISED APRIL 2000

receiver electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VIT(REC)	Differential input threshold voltage for recessive state	$V_{IC} = -2 V \text{ to } 7 V$			500	mV
VIT(DOM)	Differential input threshold voltage for dominant state	V C = -2 V to 7 V	900			ΠV
V _{hys}	Recessive-dominant input hysteresis		100	180		mV
V _{OH(RX)}	High-level output voltage	VO(DIFF) = 500 mV, I _{OH} = -400 μA	V _{CC} -0.5 V		VCC	V
V _{OL(RX)}	Low-level output voltage	V _{O(DIFF)} = 900 mV, I _{OL} = 1 mA	0		0.5	V
rI(REC)	CANH and CANL input resistance in recessive state	dc, no load	5		50	kΩ
^r l(DIFF)	Differential CANH and CANL input resistance in recessive state	dc, no load	10		100	kΩ
Ci	CANH and CANL input capacitance			20		pF
C _{i(DHL)}	Differential CANH and CANL input capacitance			10		рF

NOTE 2: All voltage values, except differential bus voltage, are measured with respect to the ground terminal.



NOTE A: The input pulse is supplied to \overline{TX} by a generator having a t_r and t_f = 5 ns.

Figure 2. Test Circuit



SLRS048A - MAY 1998 - REVISED APRIL 2000

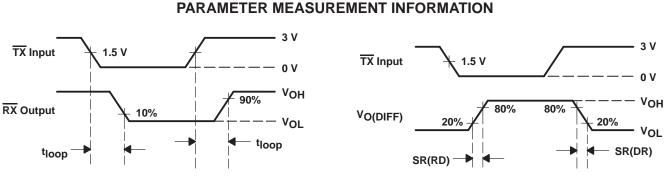
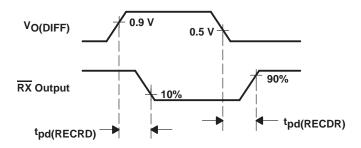


Figure 3. Loop Time

Figure 4. Slew Rate

NOTE A: The input pulse is supplied to \overline{TX} by a generator having a t_f and t_f = 5 ns.



NOTE A: The input pulse is supplied as V_{DIFF} using CANH and CANL respectively by a generator having a t_r and $t_f = 5$ ns.

Figure 5. Receiver Delay Times

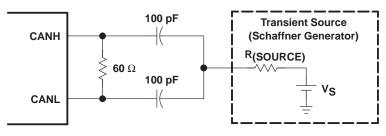


Figure 6. Transient Stress Capability Test Circuit



SLRS048A - MAY 1998 - REVISED APRIL 2000

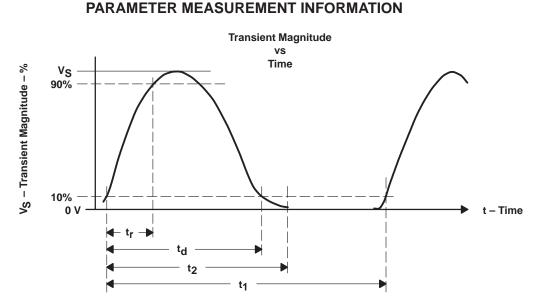


Figure 7. Transient Stress Capability Waveform

TEST PULSE	TRANSIENT MAGNITUDE VS	SOURCE IMPEDANCE RSOURCE	PULSE WIDTH ^t d (see Note 5)	PULSE RISE TIME, t _r (see Note 6)	PULSE TIME, ^t 2 (see Figure 7)	REPETITION PERIOD, t ₁ (see Figure 7)	NUMBER OF PULSES
1	–100 V	10 Ω	2 ms	1 μs	200 ms	5 s	5000
2	100 V	10 Ω	50 μs	1 μs	200 ms	5 s	5000
3a	–150 V	50 Ω	0.1 μs	5 ns	100 μs	100 μs	See Note 7
3b	100 V	50 Ω	0.1 μs	5 ns	100 μs	100 μs	See Note 7
5	60 V	1 Ω	400 ms	5 ms	—	_	1

NOTES: 5. Measured from 10% on rising edge to 10% on falling edge

6. Measured from 10% to 90% of pulse

7. Pulse package for a period of 3600 s, 10 ms pulse time, 90 ms stop time



SLRS048A - MAY 1998 - REVISED APRIL 2000

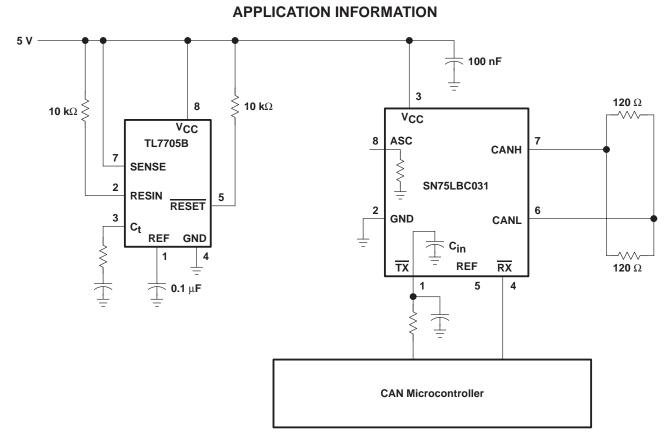


Figure 8. Typical SN75LBC031 Application



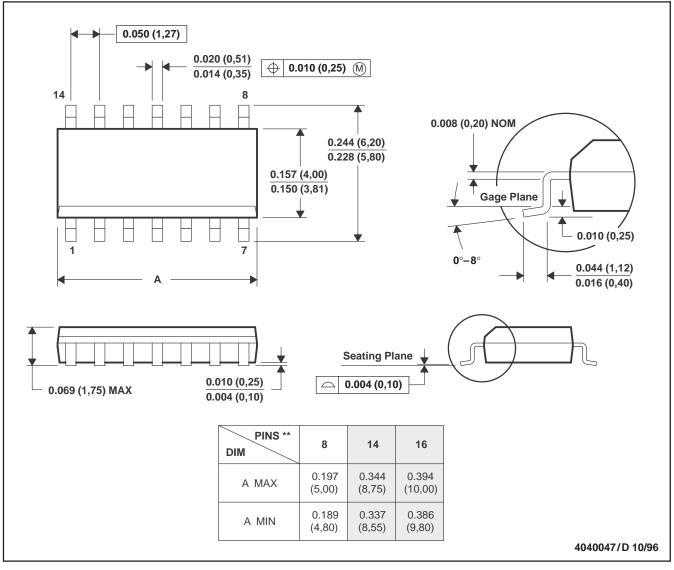
SLRS048A - MAY 1998 - REVISED APRIL 2000

MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LBC031D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65LBC031DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC031P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
SN75LBC031D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC031DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC031P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI

 $^{(1)}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

MECHANICAL DATA

MPDI001A - JANUARY 1995 - REVISED JUNE 1999



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
Low Power Wireless	www.ti.com/lpw	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2007, Texas Instruments Incorporated